· ·			
PCN Number: 20151228001 PCN Date: 1/4/2016 Title: Datasheet for TPS65263-Q1			
	Services		
Change Type:			
Assembly Site Design Wafer Bump Sit	ite		
	fer Bump Material		
Assembly Materials Part number change Wafer Bump Pro	Wafer Bump Process		
☐ Packing/Shipping/Labeling ☐ Test Process ☐ Wafer Fab Mate	erials		
☐ Wafer Fab Proce	cess		
Notification Details			
Description of Change:			
Texas Instruments Incorporated is announcing an information only notification.			
The product datasheet(s) is updated as seen in the change revision history below:			
TEXAS INSTRUMENTS			
TPS65263-Q1	UMENTS		
SLVSCS9C – DECEMBER 2014–REVISED NOVEMBER 2015 www.ti.com			
Changes from Revision B (January 2015) to Revision C			
Added more pin information for SDA and SCL			
Added more information about SDA and SCL pins			
Added Community Resources			
Device Family Change From: Change T	To:		
TPS65263-Q1 SLVSCS9B SLVSCS9	9C		
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/tps65263-q1			
Reason for Change:			
To more accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
PS65263QRHBTQ1 TPS65263QRHBTQ1			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com